

Fa6¹

Automatic Micro Assembly System

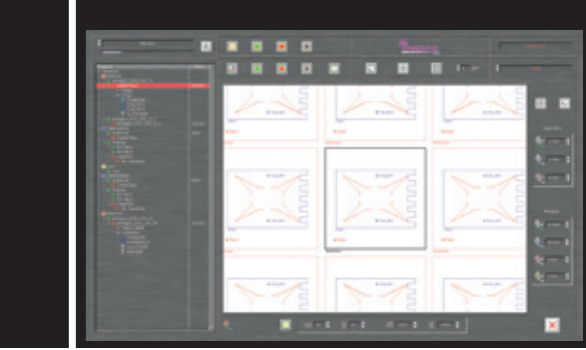
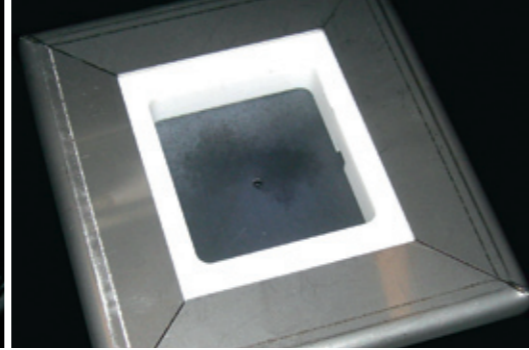
- Automatic Dispenser change
- 2x8" Wafer parallel
- Integrated Flow Box
- Customer specific modifications



AMADYNE.

GMBH

www.amadyne.net



fab¹

fab¹ is an automatic assembly system for handling virtually any kind and size of component, as well as for applying adhesives. Typical applications are pick & place-, sorting-, inspection- and test functions.

Flexibility, easy operation and optional configurations of this compact equipment permit the fabrication of standard and advanced packaging technologies like chip on board, multichip modules, chip on chip, flip chip, eutectic soldering processes etc.

fab¹ uses the latest hardware technology combined with a network transparent fully graphical control software interacting with a SQL server backend.

Key features

- 500mm x 430mm area of operations for the xy axis
- component presentation in all common forms, Wafer Pack, GEL PAK , 1 Wafer up to 12" or 2 Wafer up to 8" parallel presented or Tape Feeder
- Linux based open software architecture with SQL storage backend and various options
- basic system with ironcore linear motors and modular hardware configuration such as automatic dispenser change
- flexible system design to integrate customer specific requirements
- Integrated Flow Box with separation efficiency of 99,995%





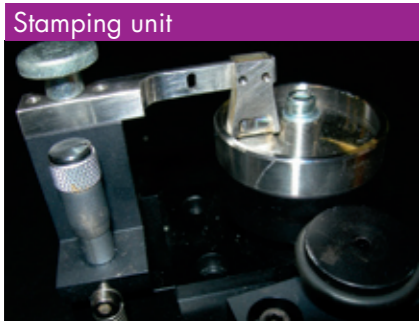
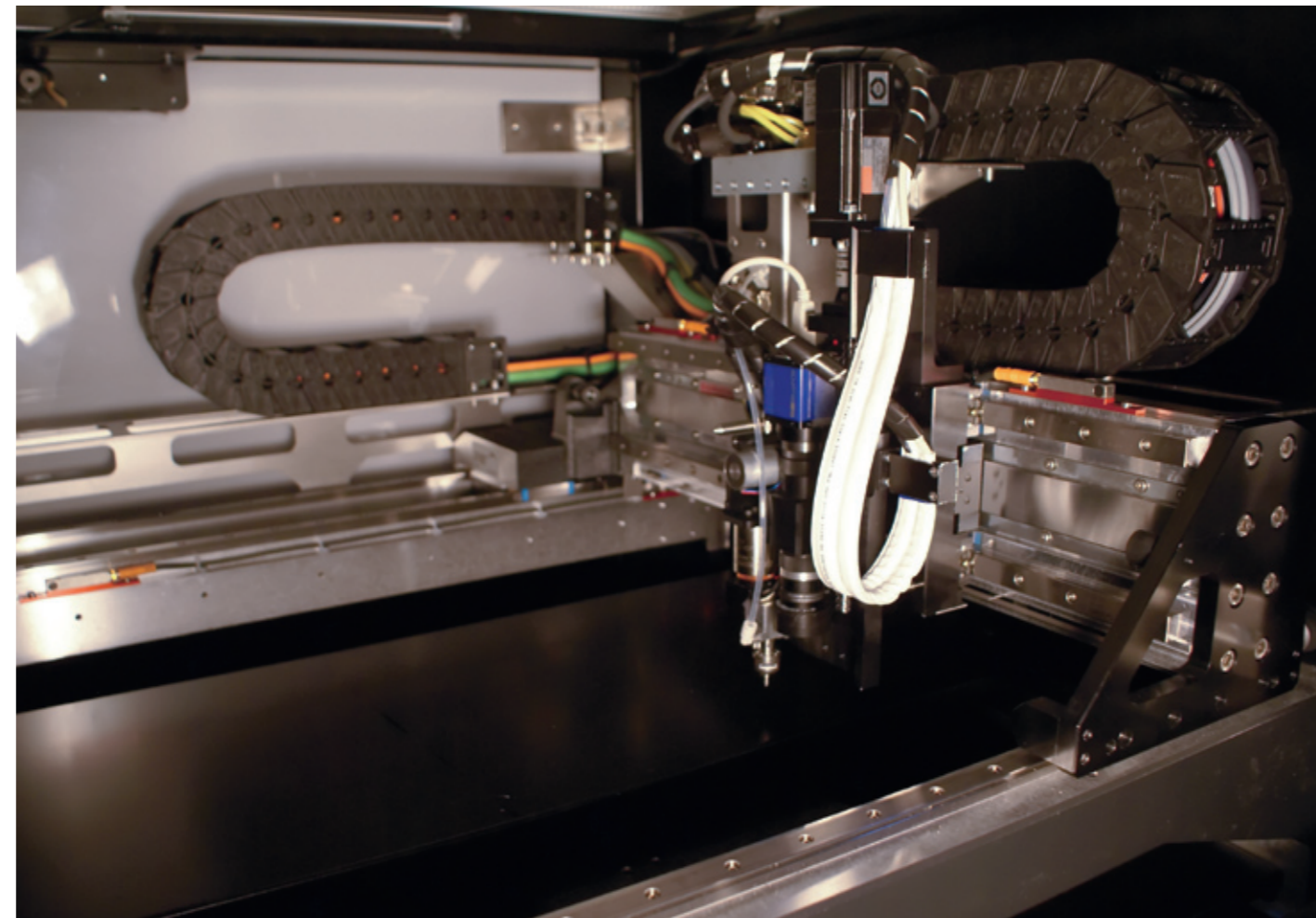
Toolbox for up to 15 tool holders

Hardware Basics

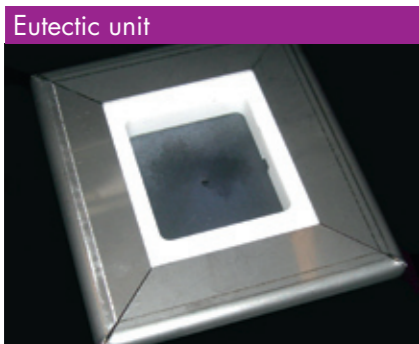
- Rugged compact steel mainframe with an embedded vibration damped aluminium casting
- Ironcore linear motors for xy axis integrated in the aluminium casting.
- PC System with dual core processor
- Integrated flow box with H14 filter

Software Basics

- Open software architecture with SQL backend
- GUI, graphical user interface supported with expert panels
- Linux-2.6 operating system
- Image recognition feature based with pattern matcher, circle-, edge- and ink dot matching
- easy to operate and program



single squeegee with selectable speed and adjustable epoxy film thickness



eutectic unit for soldering processes



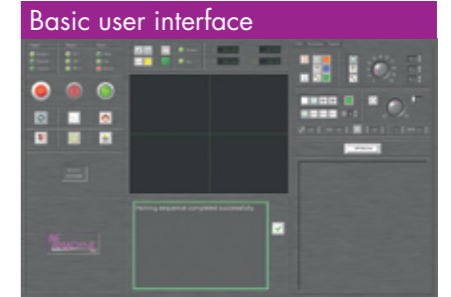
exchangeable, single- and multineedle capable for Wafer u to 12"

Options

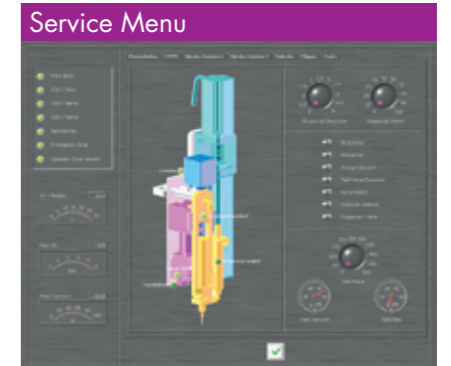
- toolbox
- eject system
- dispenser
- stamping unit
- flip chip unit
- uplooking camera
- tape feeder
- eutectic unit

Options

- Wafer mapping
- Offline Programming, CAD data import
- Inspection
- Manual Mode
- Traceability



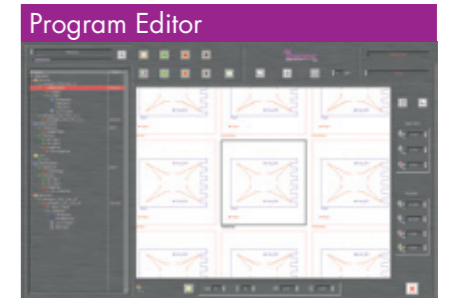
with live video, production window and status readouts



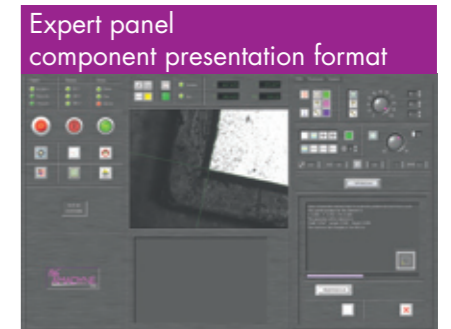
operating of actuators, display of sensor states, system diagnosis



easy adjustable process parameters for every component, display of process graph, individual control of component handling



creation of programs, display schematics of the actual applications



interactive graphical programming of the presentation forms with teach in